

SN54ABT2241, SN74ABT2241 OCTAL BUFFERS AND LINE/MOS DRIVERS WITH 3-STATE OUTPUTS

SCBS233B – JANUARY 1991 – REVISED JANUARY 1997

- Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs

description

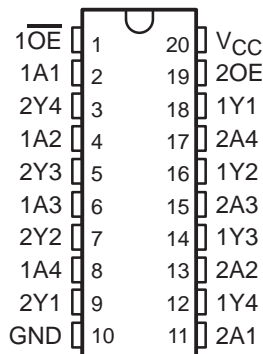
These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the SN54ABT2240, SN74ABT2240A and 'ABT2244A, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable (\overline{OE}) inputs, and complementary OE and \overline{OE} inputs. These devices feature high fan-out and improved fan-in.

The outputs, which are designed to sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

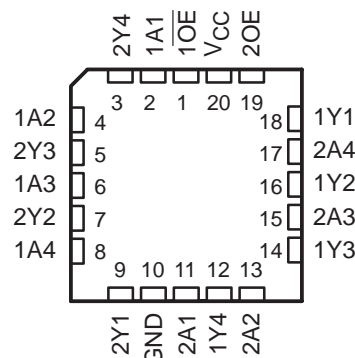
To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN54ABT2241 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABT2241 is characterized for operation from -40°C to 85°C .

SN54ABT2241 . . . J PACKAGE
SN74ABT2241 . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)



SN54ABT2241 . . . FK PACKAGE
(TOP VIEW)



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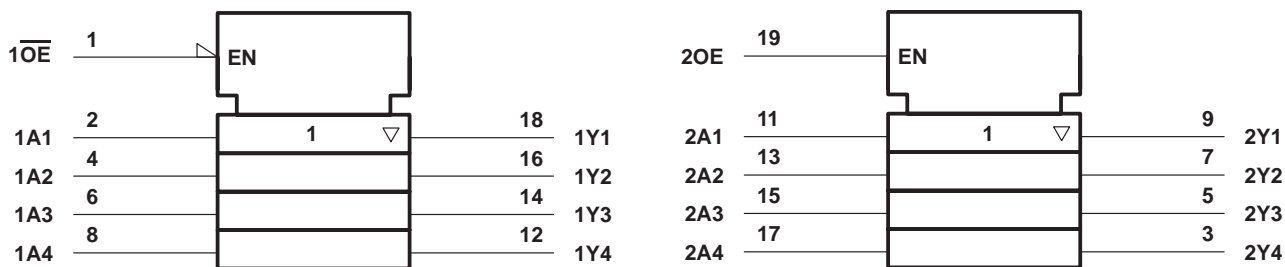
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FUNCTION TABLES

INPUTS		OUTPUT
1OE	1A	1Y
L	H	H
L	L	L
H	X	Z

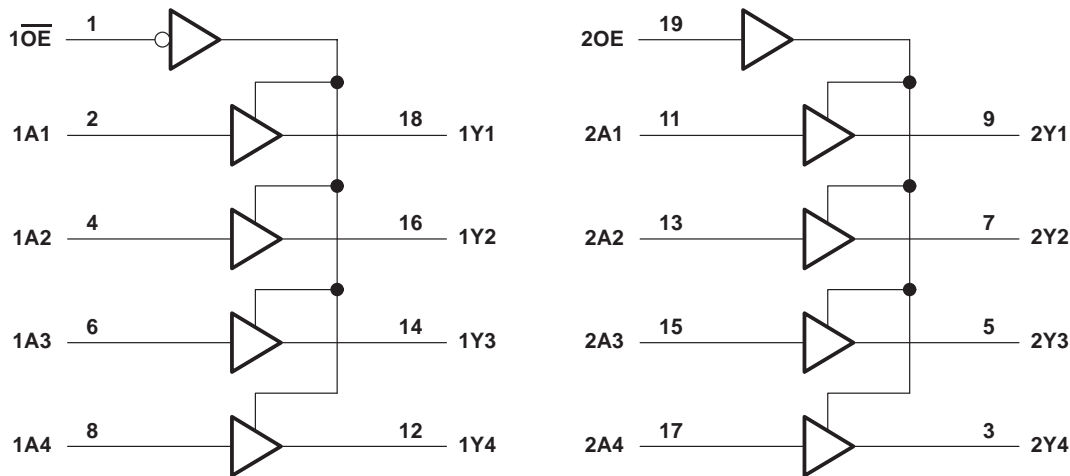
INPUTS		OUTPUT
2OE	2A	2Y
H	H	H
H	L	L
L	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



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recommended operating conditions (see Note 3)

		SN54ABT2241		SN74ABT2241		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		-24		-32	mA
I_{OL}	Low-level output current		12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5	5	ns/V
T_A	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	$T_A = 25^\circ\text{C}$			SN54ABT2241		SN74ABT2241		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$			-1.2		-1.2		-1.2	V
V_{OH}		$V_{CC} = 4.5\text{ V}$, $I_{OH} = -3\text{ mA}$	2.5			2.5		2.5		V
		$V_{CC} = 5\text{ V}$, $I_{OH} = -3\text{ mA}$	3			3		3		
		$V_{CC} = 4.5\text{ V}$	$I_{OH} = -24\text{ mA}$	2		2				
			$I_{OH} = -32\text{ mA}$	2*				2		
V_{OL}		$V_{CC} = 4.5\text{ V}$, $I_{OL} = 12\text{ mA}$			0.8		0.8		0.8	V
V_{hys}				100						mV
I_I		$V_{CC} = 5.5\text{ V}$, $V_I = V_{CC}$ or GND		± 1			± 1		± 1	μA
I_{OZH}		$V_{CC} = 5.5\text{ V}$, $V_O = 2.7\text{ V}$		50		50		50		μA
I_{OZL}		$V_{CC} = 5.5\text{ V}$, $V_O = 0.5\text{ V}$		-50		-50		-50		μA
I_{off}		$V_{CC} = 0$, V_I or $V_O \leq 4.5\text{ V}$		± 100				± 100		μA
I_{CEX}		$V_{CC} = 5.5\text{ V}$, $V_O = 5.5\text{ V}$		50		50		50		μA
$I_{O\ddagger}$		$V_{CC} = 5.5\text{ V}$, $V_O = 2.5\text{ V}$	-50	-100	-180	-50	-180	-50	-180	mA
I_{CC}		$V_{CC} = 5.5\text{ V}$, $I_O = 0$, $V_I = V_{CC}$ or GND	Outputs high		1	250	250	250	μA	
	Outputs low		24	30	30	30	mA			
	Outputs disabled		0.5	250	250	250	μA			
$\Delta I_{CC}\S$	Data inputs	$V_{CC} = 5.5\text{ V}$, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled		1.5		1.5	1.5	mA	
			Outputs disabled		0.05		0.05	0.05		
	Control inputs	$V_{CC} = 5.5\text{ V}$, One input at 3.4 V, Other inputs at V_{CC} or GND			1.5		1.5	1.5		
C_i	C_i	$V_I = 2.5\text{ V}$ or 0.5 V			3				pF	
C_o	C_o	$V_O = 2.5\text{ V}$ or 0.5 V			8.5				pF	

* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at $V_{CC} = 5\text{ V}$.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5$ V, $T_A = 25^\circ$ C			SN54ABT2241		SN74ABT2241		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	3	4.3	1	4.8	1	4.7	ns
t_{PHL}			1	4.3	5.3	1	5.7	1	5.6	
t_{PZH}	OE or \overline{OE}	Y	1.1	3.5	4.8	1.1	6.1	1.1	5.8	ns
t_{PZL}			2.1	6.2	7.6	2.1	8.6	2.1	8.4	
t_{PHZ}	OE or \overline{OE}	Y	1.7	4.2	5.6	1.7	6.7	1.7	6.6	ns
t_{PLZ}			1.7	3.9	5.8	1.7	6.9	1.7	6.4	

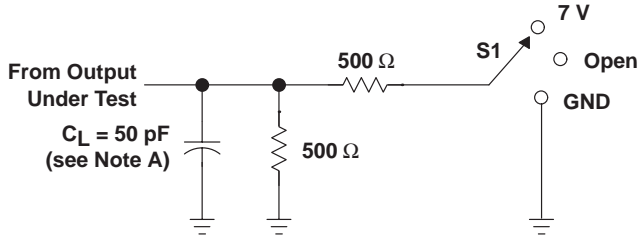
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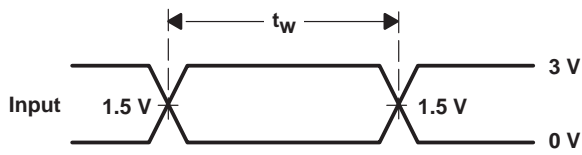
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PARAMETER MEASUREMENT INFORMATION

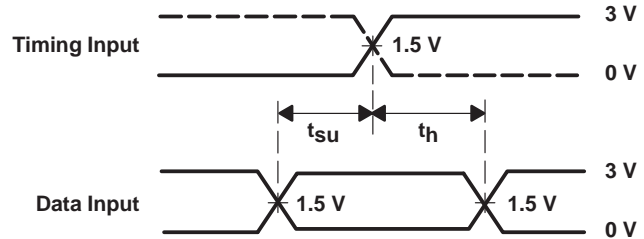


LOAD CIRCUIT

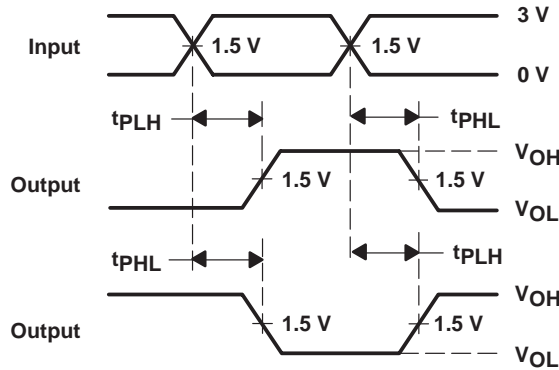
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



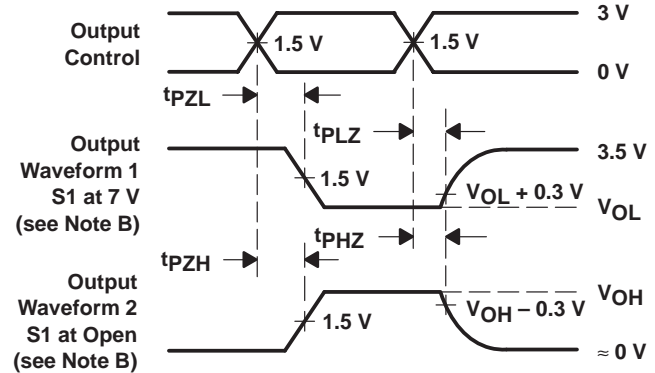
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ABT2241DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74ABT2241DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2241DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2241DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2241DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2241DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2241DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2241DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2241DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2241DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2241N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ABT2241NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ABT2241NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2241NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2241NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2241PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI
SN74ABT2241PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2241PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2241PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and

package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

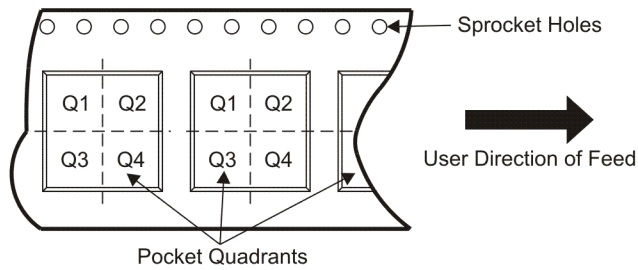
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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT2241DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ABT2241DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ABT2241PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT2241DBR	SSOP	DB	20	2000	346.0	346.0	33.0
SN74ABT2241DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74ABT2241PWR	TSSOP	PW	20	2000	346.0	346.0	33.0

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

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